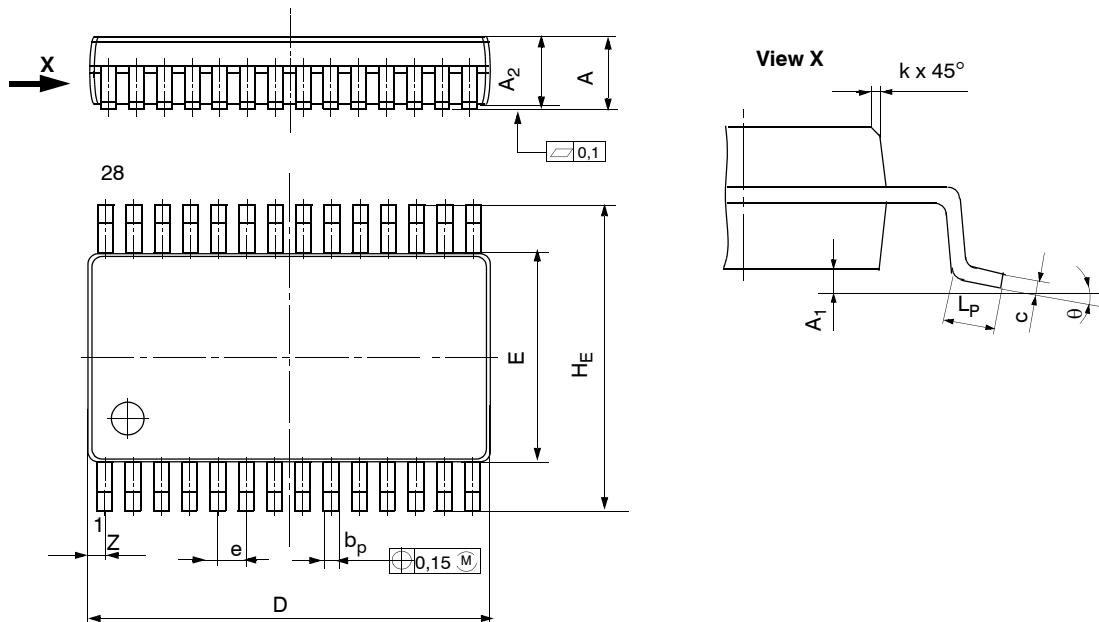
	Package SSOP28 (5,3 mm)	MDS 762
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Dimensions in millimetres

Based on JEDEC JEP95: MO-150

1 Dimensions

Dimensions of Sub-Group B1	
A_{max}	1,99
b_{Pmin}	0,25
b_{Pmax}	0,38
e_{nom}	0,65
H_{Emin}	7,65
H_{Emax}	7,90
L_{Pmin}	0,63
Z_{max}	1,22

- 2 Weight** $\leq 0,4$ g
- 3 Package Body Material** Low Stress Epoxy
- 4 Lead Material** FeNi-Alloy or Cu-Alloy
- 5 Lead Finish** solder plating
- 6 Lead Form** Z-bends

Dimensions of Sub-Group C1	
A_{min}	1,73
A_{1min}	0,05
A_{1max}	0,21
A_{2min}	1,68
A_{2max}	1,78
c_{min}	0,09
c_{max}	0,20
D_{min}^*	10,07
D_{max}^*	10,33
E_{min}^*	5,20
E_{max}^*	5,38
k_{min}	0,25
θ_{min}	0°
θ_{max}	10°

* without mold-flash

Zentrum Mikroelektronik Dresden AG		
Editor: signed Schoder	Date: 25.01.2002	Doc-No. QS-000762-HD-01
Check: signed Marx	Quality: signed Lorenz	